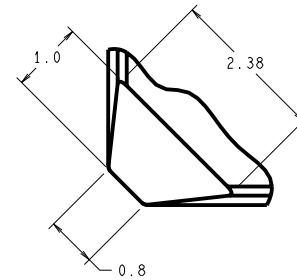
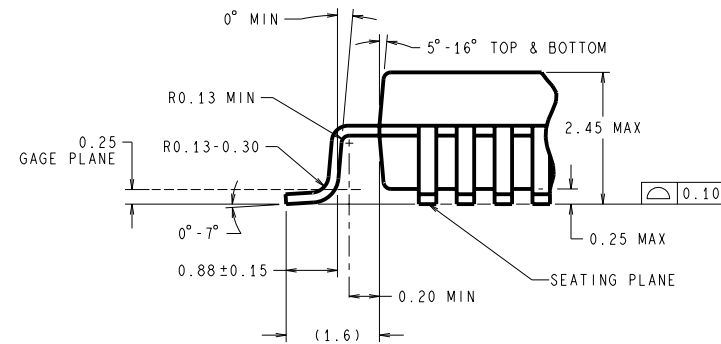


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW PER JEDEC MS-022.	11037	07/24/95	DEG/



OPTIONAL PIN 1 CORNER
FROM ASAT ONLY
SCALE: 21X



DETAIL A
TYP. SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15mm.
- REFERENCE JEDEC STANDARD MS-022, VARIATION BC,
DATED FEB/95.

APPROVALS		DATE	National Semiconductor		
DRAWN	<i>D. E. Grady</i>	07/24/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DTG. CHK.			POFP, JEDEC METRIC, 14 X 14 X 2.0mm, 80 LEAD		
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VJE80A	E
DO NOT SCALE DRAWING			SHEET 1 of 1		